

SECTION 2. FORMS PTO/SB/08A and 08B (formerly Form PTO-1449)**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Lawrence E. Felton, et al Attorney Docket: 2559/176
Serial No: Art Group Unit:
Date Filed: September 8, 2003 Examiner Name:
Invention: Wafer Level Capped Sensor

**LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION DISCLOSURE STATEMENT**

U.S. PATENT DOCUMENTS					
Examiner Initials	Reference Number	Document Number	Issue Date	Inventor	Class/Subclass
	AA	US 5,326,726	Jul. 5, 1994	Tsang et al.	437/228
	AB	US 5,345,824	Sep. 13, 1994	Sherman et al.	73/517B
	AC	US 5,314,572	May 24, 1994	Core et al.	156/643
	AD	US 5,417,111	May 23, 1995	Sherman et al.	73/517 R
	AE	US 5,620,931	Apr. 15, 1997	Tsang et al.	438/50
	AF	US 5,540,095	Jul. 30, 1996	Sherman et al.	73/514.18
	AG	US 6,448,109 B1	Sep. 10, 2002	Karpman	438/108

FOREIGN PATENT DOCUMENTS						
Examiner Initials	Reference Number	Country Code	Document Number	Publication Date	Patentee or Applicant	Class/Subclass

OTHER DOCUMENTS			
Examiner Initials	Reference Number	Author	Title of Article, Title of Journal, Volume Number, Page Numbers, Date
	AH	Shellcase	Shellcase-ShellBGA, p. 1-2, 12/2/2002
	AI	Doron Teomim, et al	An Innovative Approach to wafer-level MEMS packaging, Solid State Technology-semiconductor manufacturing and wafer fabrication, p. 1-4, 12/2/2002
	AJ	Katarina Boustedt, et al	Flip Chip as an Enabler for MEMS Packaging, 2002 Electronic Components and Technology Conference, p. 124-128, 2002
	AK	White Paper	MEMS: Mainstream Process Integration, Ziptronics

	AL	Seong Joon OK, et al	Generic, Direct-Chip Attach MEMS Packaging Design with High Density and Aspect Ration through-Wafer Electrical Interconnect, 2002 Electronic Components and Technology Conference, 2002
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Examiner Signature: _____

Date Considered: _____

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation *if not* in conformance and not considered. Include copy of this form with next communication to applicant.